

Title (en)

Reception device for a backplane

Title (de)

Vorrichtung zur Aufnahme einer Rückwandleiterplatte

Title (fr)

Dispositif de réception pour un circuit imprimé

Publication

**EP 1261077 A3 20060823 (DE)**

Application

**EP 02006872 A 20020326**

Priority

DE 10124814 A 20010521

Abstract (en)

[origin: EP1261077A2] The arrangement has a contact arrangement for making contact between the circuit board (16) and the housing for units containing electronic and/or electrical units. The contact arrangement is in the form of sprung contact elements protruding in the direction of a screened surface of the circuit board. The contact elements (17) are arranged on a contact side of the arrangement facing the screened board surface.

IPC 8 full level

**H01R 13/648** (2006.01); **H01R 13/658** (2006.01)

CPC (source: EP)

**H01R 13/6485** (2013.01); **H01R 13/6582** (2013.01); **H01R 13/6594** (2013.01)

Citation (search report)

- [XY] DE 29808620 U1 19980806 - SIEMENS AG [DE]
- [YX] PATENT ABSTRACTS OF JAPAN vol. 018, no. 687 26 December 1994 (1994-12-26)

Designated contracting state (EPC)

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DOCDB simple family (publication)

**EP 1261077 A2 20021127**; **EP 1261077 A3 20060823**; **EP 1261077 B1 20080611**; DE 10124814 A1 20021205; DE 10124814 B4 20051208; DE 50212354 D1 20080724

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